



US 20220386464A1

(19) **United States**(12) **Patent Application Publication**
IFIS et al.(10) **Pub. No.: US 2022/0386464 A1**(43) **Pub. Date: Dec. 1, 2022**(54) **COMPONENT CARRIER
INTERCONNECTION AND
MANUFACTURING METHOD***H05K 3/18* (2006.01)*H05K 3/36* (2006.01)(52) **U.S. CL.**CPC *H05K 1/144* (2013.01); *H05K 1/113*
(2013.01); *H05K 3/1283* (2013.01); *H05K*
3/4623 (2013.01); *H05K 3/185* (2013.01);
H05K 3/368 (2013.01); *H05K 2201/041*
(2013.01); *H05K 2201/09481* (2013.01); *H05K*
2201/09563 (2013.01); *H05K 2203/072*
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Jun. 1, 2021 (EP) 21177178.7

Publication Classification(51) **Int. Cl.***H05K 1/14* (2006.01)*H05K 1/11* (2006.01)*H05K 3/12* (2006.01)*H05K 3/46* (2006.01)

(57)

ABSTRACT

A component carrier assembly includes a first component carrier having a first electrically insulating layer structure and a via in the first electrically insulating layer structure, where the via is at least partially filled with electrically conductive material and where an upper part of the via extends beyond an outer main surface of the first component carrier; and a second component carrier having a second electrically insulating layer structure, and an electrically conductive adhesive material that is at least partially embedded in the second electrically insulating layer structure. The first component carrier and the second component carrier are interconnected and the upper part of the via at least partially penetrates into the electrically conductive adhesive material.

